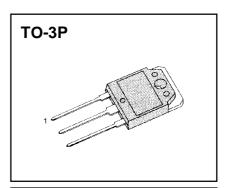
# SGH23N60UF

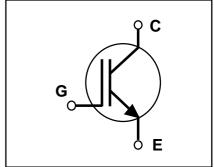
## **FEATURES**

- \* High Speed Switching
- \* Low Saturation Voltage
  - : V<sub>CE</sub>(sat) = 1.95 V (@ Ic=12A)
- \* High Input Impedance

## **APPLICATIONS**

- \* AC & DC Motor controls
- \* General Purpose Inverters
- \* Robotics, Servo Controls
- \* Power Supply
- \* Lamp Ballast





## **ABSOLUTE MAXIMUM RATINGS**

Symbol	Characteristics	Rating	Units
V <sub>CES</sub>	Collector-Emitter Voltage	600	V
$V_{GES}$	Gate-Emitter Voltage	±20	V
I <sub>C</sub>	Collector Current @ Tc = 25°C	23	Α
	Collector Current @ Tc = 100°C	12	Α
I <sub>CM (1)</sub>	Pulsed Collector Current	92	Α
P <sub>C</sub>	Maximum Power Dissipation @Tc = 25°C	100	W
	Maximum Power Dissipation @Tc = 100°C	40	W
Tj	Operating Junction Temperature	-55 ~ 150	°C
Tstg	Storage Temperature Range -55 ~ 150		°C
TL	Maximum Lead Temp. For Soldering 300 °C		°C
	Purposes, 1/8" from case for 5 seconds		

Notes:(1) Repetitive rating: Pulse width limited by max. junction temperature



# **ELECTRICAL CHARACTERISTICS**

(Tc=25°C,Unless Otherwise Specified)

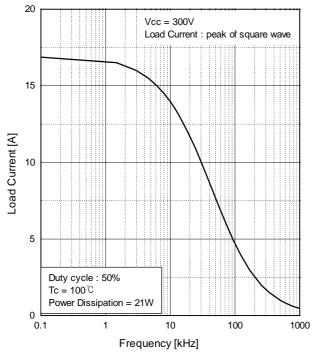
Symbol	Characteristics	Test Conditions	Min	Тур	Max	Units
BV <sub>CES</sub>	C - E Breakdown Voltage	V <sub>GE</sub> = 0V , I <sub>C</sub> = 250uA	600	-	-	V
$\Delta V_{\text{CES}/}$	Temperature Coeff. of	$V_{GE} = 0V$ , $I_C = 1mA$	-	0.6	-	V/°C
$\DeltaT_J$	Breakdown Voltage					
$V_{GE(th)}$	G - E threshold voltage	$I_C = 12\text{mA}$ , $V_{CE} = V_{GE}$	4.0	5.5	7.5	V
I <sub>CES</sub>	Collector cutoff Current	$V_{CE} = V_{CES}$ , $V_{GE} = 0V$	-	-	250	uA
I <sub>GES</sub>	G - E leakage Current	$V_{GE} = V_{GES}$ , $V_{CE} = 0V$	-	-	100	nA
V <sub>CE</sub> (sat)	Collector to Emitter	Ic=12A, V <sub>GE</sub> = 15V	-	1.95	2.6	٧
	saturation voltage	Ic=23A, V <sub>GE</sub> = 15V	-	2.6	-	٧
Cies	Input capacitance	V <sub>GE</sub> = 0V , f = 1MHz	-	720	-	pF
Coes	Output capacitance	V <sub>CE</sub> = 30V	-	65	-	pF
Cres	Reverse transfer capacitance		-	26	-	pF
td(on)	Turn on delay time	V <sub>CC</sub> = 300V , I <sub>C</sub> = 12A	-	12	-	ns
tr	Turn on rise time	V <sub>GE</sub> = 15V	-	20	-	ns
td(off)	Turn off delay time	$R_{G} = 23\Omega$	-	55	85	ns
tf	Turn off fall time	Inductive Load	-	100	220	ns
Eon	Turn on Switching Loss		-	0.11	-	mJ
Eoff	Turn off Switching Loss		-	0.19	-	mJ
Ets	Total Switching Loss	]	-	0.3	0.5	mJ
Qg	Total Gate Charge	Vcc = 300V	-	48	72	nC
Qge	Gate-Emitter Charge	V <sub>GE</sub> = 15V	-	11	16	nC
Qgc	Gate-Collector Charge	Ic = 12A	-	14	21	nC
Le	Internal Emitter Inductance	Measured 5mm from PKG	-	7.5	-	nH



# THERMAL RESISTANCE

Symbol	Characteristics	Min	Тур	Max	Units
R <sub>θ</sub> JC	Junction-to-Case	-	-	1.2	°C/W
R <sub>e</sub> JA	Junction-to-Case	-	-	40	°C/W
R <sub>θ</sub> CS	Case-to-Sink	-	0.24	-	°C/W





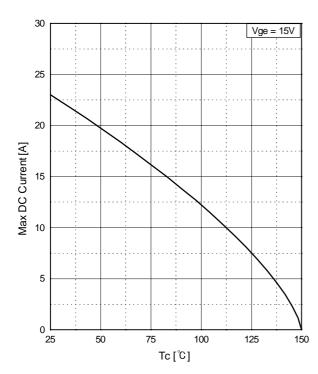
100
80
Tc = 25°C

Tc = 100°C

40
20
0 2 4 6 8 10

Fig.1 Typical Load Current vs. Frequency

Fig.2 Typical Output Characteristics





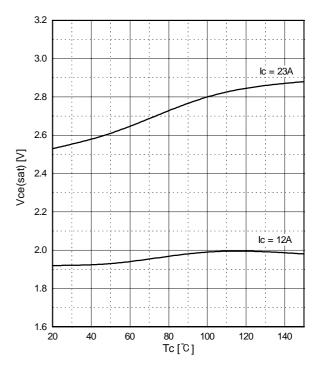


Fig.4 Collector to Emitter Voltage vs. Case Temperature



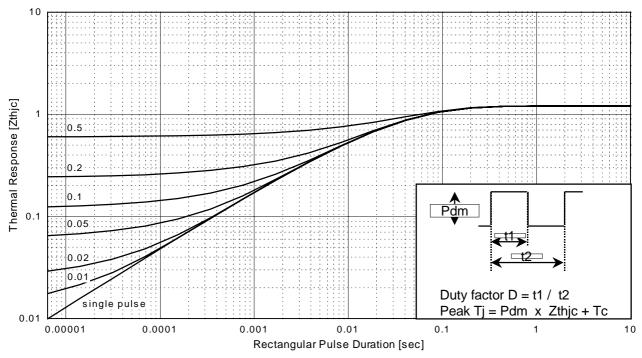


Fig.5 Maximum Effective Transient Thermal Impedance, Junction to Case

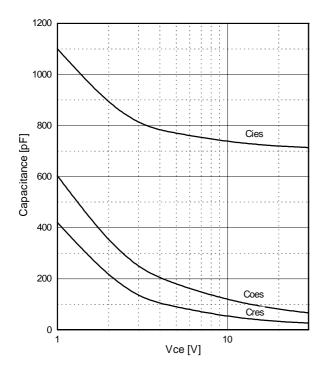


Fig.6 Typical Capacitance vs.
Collector to Emitter Voltage

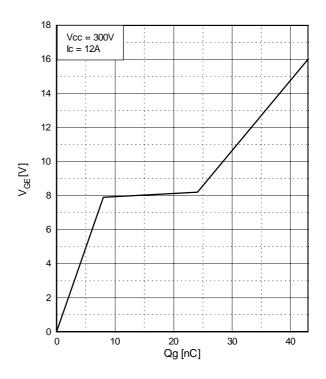


Fig.7 Typical Gate Charge vs. Gate to Emitter Voltage



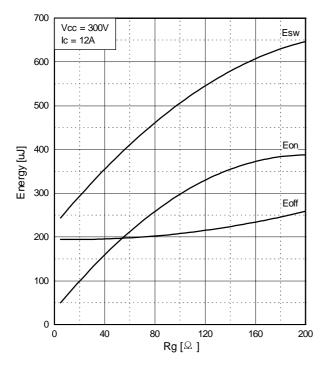


Fig.8 Typical Switching Loss vs. Gate Resistance

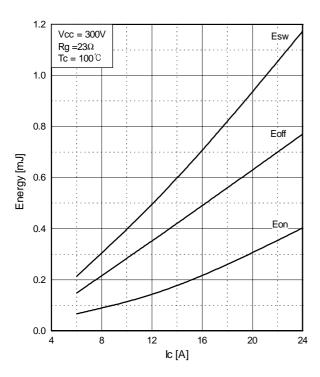


Fig.10 Typical Switching loss vs.
Collector to Emitter Current

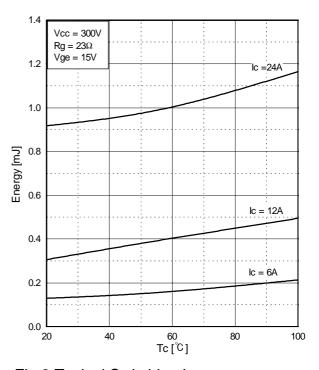


Fig.9 Typical Switching Loss vs. Case Temperature

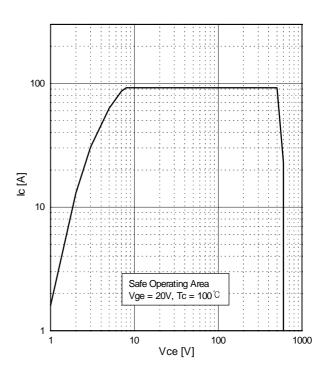


Fig.11 Turn-off SOA



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